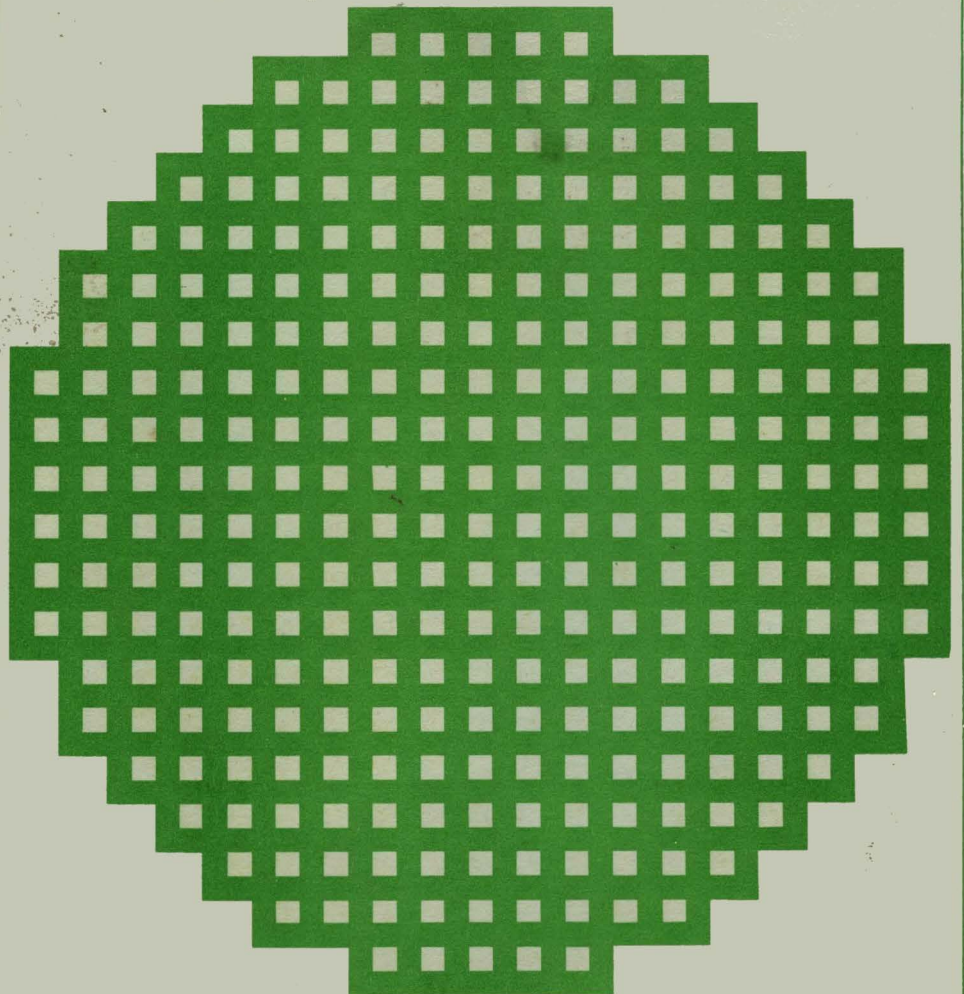


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East Fishkill Facility
Hopewell Junction, New York

Purchased Components Manual
Passives



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PASSIVE COMPONENTS MANUAL

PREFACE

This publication is designed to serve as a guide and engineering reference for users of passive electronic components. It includes descriptions, performance characteristics, and general application information for major passive discrete and hybrid type electronic component families presently purchased by component procurement.

This publication is organized by component family and is divided into seven major sections: resistors, potentiometers, capacitors, networks, magnetics, relays, and crystals. A part number detail catalog is included at the end of each product section for reference.

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